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## ABSTRACT

### MOLDING SYSTEM FOR SEMICONDUCTOR PACKAGES

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The present invention provides a molding system as well as a method for encapsulating semiconductor packages, wherein a cavity plate is kept at a desired temperature during molding. The system includes a mold comprising a first mold piece and a second mold piece adapted to define a mold cavity for enclosing one or more semiconductor devices for molding, and a cavity plate adapted for mounting in the cavity to introduce encapsulation material to the semiconductor device(s). The system also includes retaining means adapted selectively to hold the cavity plate against the first mold piece or the second mold piece whereby to maintain the cavity plate at the desired temperature.

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(Fig. 1)



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